

Inventor: Chris Parfeniuk et. al.

Title: Methods of Bonding First and Second Masses to One Another, and Methods of Bonding Physical Vapor Deposition Target Materials to Backing Plate Materials

Assignee: Honeywell International, Inc.



## INFORMATION DISCLOSURE STATEMENT PURSUANT TO 37 C.F.R. §§1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a continuation of co-pending application Serial No. 09/057,152 filed April 7, 1998. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2). No admission is made regarding whether all the submitted references are prior art.

Citation of these references is respectfully requested.

2	Respectfully submitted,
3	Dated: /// Attorney:
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